

/ Descriptions

2A

ABS/LBF

2A Surface Mount Glass Passivated Bridge Rectifier, ABS/LBF thin package.

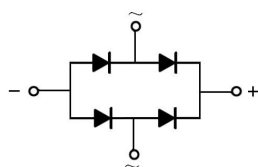
/ Features

Glass Passivated Chip Junction, Reverse Voltage :100 to 1000V, Forward Current: 2.0A, Fast reverse recovery time, Designed for Surface Mount Application. Halogen free product.

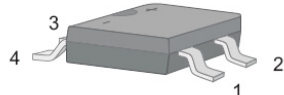
/ Applications

General purpose.

/ Equivalent Circuit

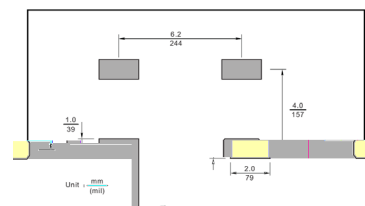


/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

The recommended mounting pad size



/ Marking

See Marking Instructions.

Parameter	Symbol	Rating	Unit
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I Electrical Characteristic Curve

Fig.1 Average Rectified Output Current Derating Curve

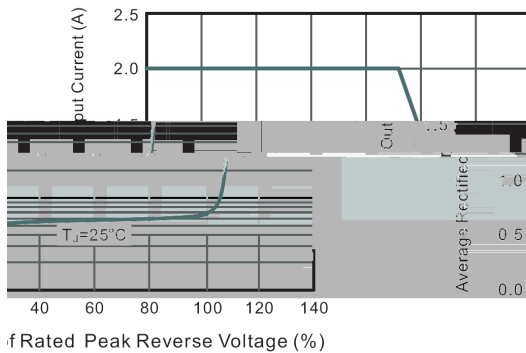


Fig.2 Typical Reverse Characteristics

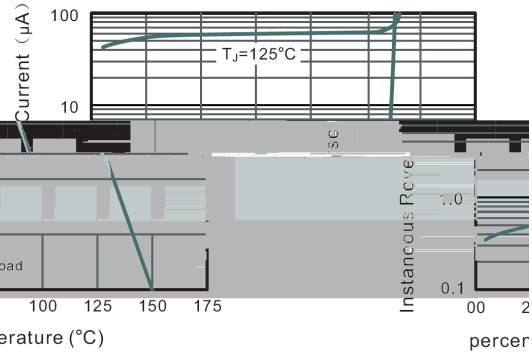


Fig.3 Typical Junction Capacitance

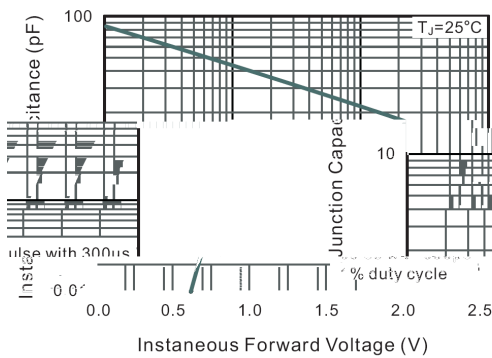


Fig.4 Typical Instantaneous Forward Characteristics

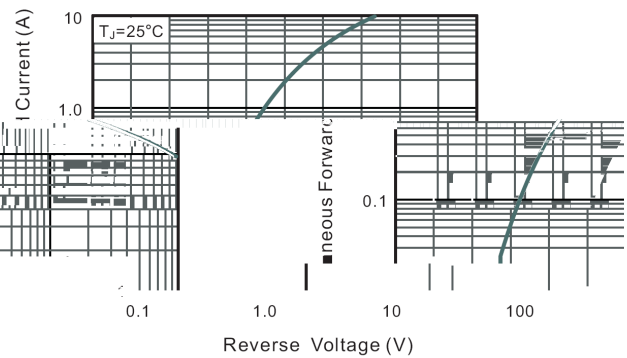
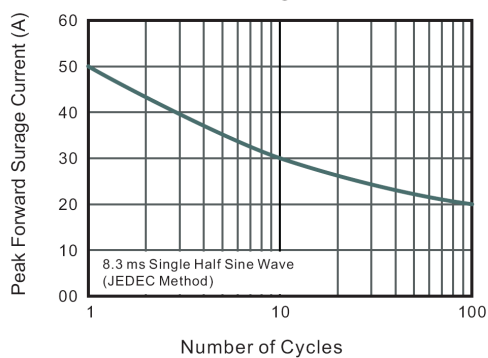
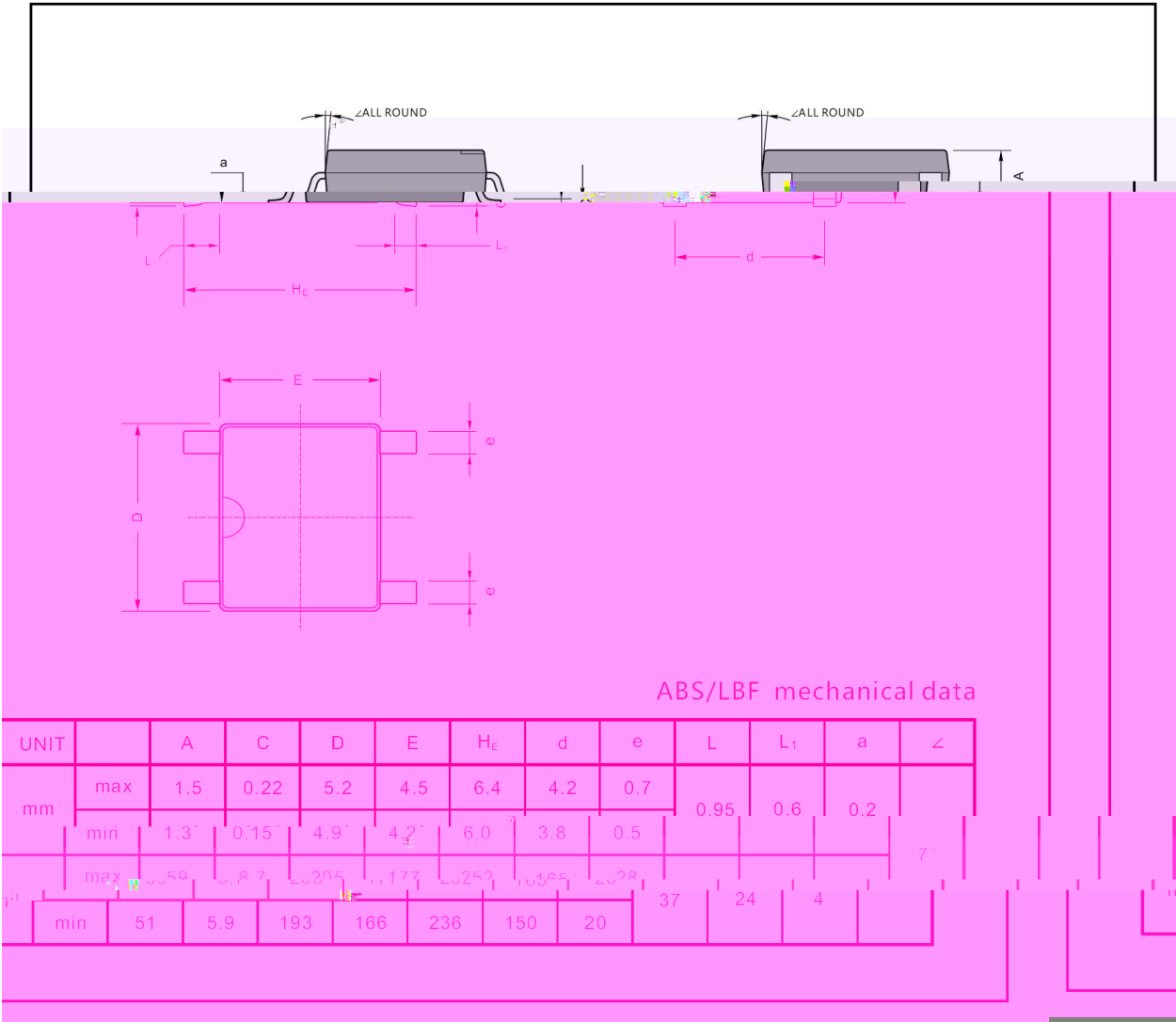


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



/ Package Dimensions

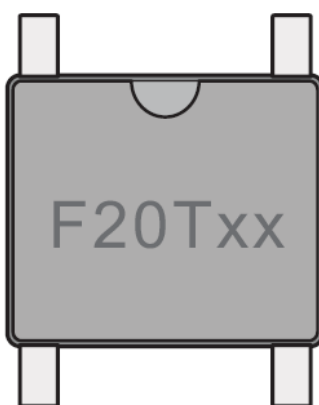
ABS/LBF



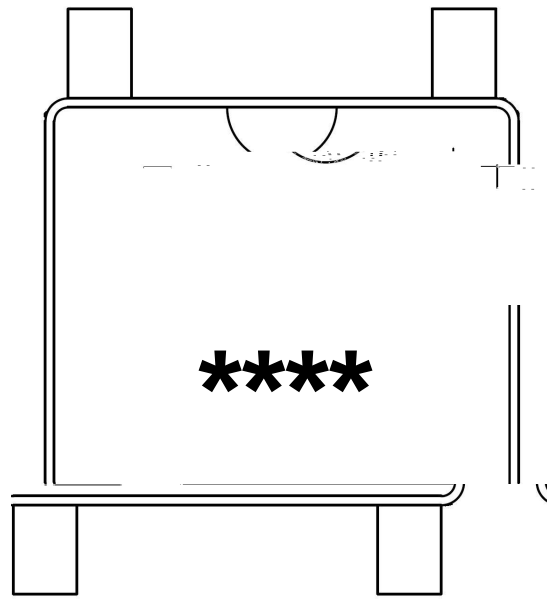
/ Marking Instructions

Marking

Type number	Marking code
FTB1S-20	F20T1
FTB2S-20	F20T2
FTB4S-20	F20T4
FTB6S-20	F20T6
FTB8S-20	F20T8
FTB10S-20	F20T10



/ Marking Instructions



F20T1

1 *

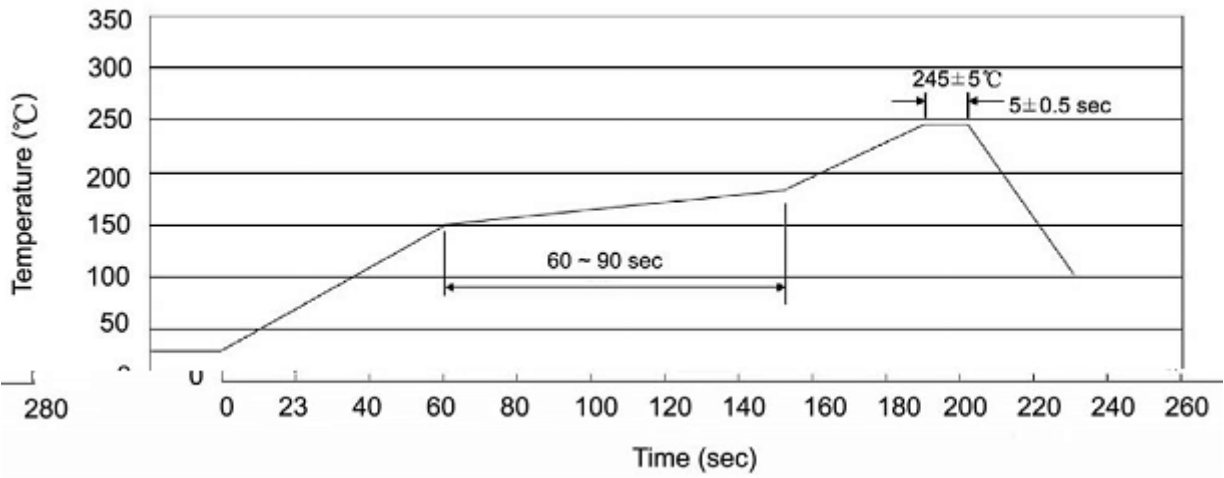
3 *

Note:

F20T1 Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No Code

() /



Note:

- 1

25 150

60 90sec;

1.Preheating:25~150 , Time:60~90sec.
- 2

245 5

5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260 5 Time:10 1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	5000	2	10000	5	50000	13 ×15	336X336X40	380X335X366

/ Notices